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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

T. MIYAMOTO et al

Serial No. 09/530,490

Group Art Unit: 2827

Filed: April 28, 2000

Examiner: D. Graybill

For: SEMICONDUCTOR DEVICE AND PROCESS FOR  
MANUFACTURING THE SAME

PRELIMINARY AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed February 19, 2002, please amend the above-identified application as follows. A Continued Prosecution Application is being filed herewith.

IN THE CLAIMS

Please rewrite claim 34 as set forth below.

C<sub>1</sub> 34. (Amended) A chip scale package, provided by dividing a semiconductor wafer along scribe lines defining a plurality of chip scale package forming areas in said semiconductor wafer, comprising:

(a) a semiconductor chip having a main surface, a rear surface opposite to said main surface and a surface

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(wh) passivation film of a silicon nitride film to cover said main surface, said semiconductor chip having a plurality of semiconductor elements and bonding pads formed on said main surface thereof, said bonding pads being exposed from said surface passivation film;

(b) an elastomer layer of a polyimide film formed on said surface passivation film to cover said main surface of said semiconductor chip and to expose said bonding pads, said elastomer layer having an elastic modulus relatively lower than said surface passivation film;

(c) conductive layers formed on said elastomer layer, first ends of said conductive layers being disposed on said elastomer layer and second ends of said conductive layers being electrically connected to the corresponding ones of said bonding pads; and

(d) a plurality of bump electrodes formed on said elastomer layer, said plurality of bump electrodes being electrically connected to said first ends of said conductive layers.

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**REMARKS**

Claim 34 has been amended. No claims have been canceled or added. Accordingly, claims 34-37 are currently pending in the application.

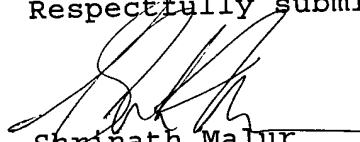
Serial No. 09/530,490

H-914

Applicants request the Examiner to contact the undersigned by telephone to set up an interview in order to speed the prosecution of this application.

Reconsideration is respectfully requested.

Respectfully submitted,



Shrinath Malur  
Registration No. 34,663  
Attorney for Applicants

MATTINGLY, STANGER & MALUR  
1800 Diagonal Rd., Suite 370  
Alexandria, Virginia 22314  
(703) 684-1120  
Date: June 18, 2002